



Telink

Telink Semiconductor (Shanghai) CO., LTD  
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Composition Table									
To: TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.									
From: Suzhou Zhen Kun Technology Limited									
Product Name: TLSR8366ET24									
Weight(Unit): 59.6600 mg									
Date: 2024/8/7									
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	1.9400	Silicon	7440-21-3	1.9400	100.00%	3.25%	1000000
Lead Frame	A194	Ningbo Kangqiang	21.6400					36.27%	
				Cu	7440-50-8	20.5104	94.78%	34.38%	947799
				Fe	7349-89-6	0.4932	2.28%	0.83%	22790
				Pb	7439-92-1	0.0000	0.00%	0.00%	1
				p	7723-14-0	0.0054	0.03%	0.01%	250
				Zn	7440-66-6	0.0273	0.13%	0.05%	1260
				Ag	7440-22-4	0.6038	2.79%	1.01%	27900
Epoxy	4900WY	Resonac Corporation	0.4500					0.75%	
				Acrylic resin	Trade secret	0.0473	10.50%	0.08%	105000
				polybutadiene derivative	Trade secret	0.0180	4.00%	0.03%	40000
				Epoxy resin	Trade secret	0.0045	1.00%	0.01%	10000
				Acrylate	Trade secret	0.0360	8.00%	0.06%	80000
				Peroxide	Trade secret	0.0023	0.50%	0.00%	5000
				Additive	Trade secret	0.0045	1.00%	0.01%	10000
				Siliver	7440-22-4	0.2025	45.00%	0.34%	450000
	Al	7429-90-5	0.1350	30.00%	0.23%	300000			
Wire	CW11	Wiretech	0.1000					0.17%	
				Ag	7440-22-4	0.0990	99.0000%	0.17%	990000
				Secret	Trade Secret	0.0010	1.0000%	0.00%	10000
Mold Compound	G700LA	Sumitomo	34.6200					58%	
				Epoxy Resin	Trade Secret	2.5965	7.50%	4.35%	75000
				Phenol Resin	Trade Secret	1.0386	3.00%	1.74%	30000
				Silica(Amorphous) A	60676-86-0	27.3325	78.95%	45.81%	789500
				Silica(Amorphous) B	7631-86-9	3.4620	10.00%	5.80%	100000
				Carbon Black	1333-86-4	0.1904	0.55%	0.32%	5500
Plating	TIN	GHT	0.9100					1.53%	
				Tin	7440-31-5	0.9099	99.99%	1.53%	999900
				Others	Trade Secret	0.0001	0.01%	0.00%	100
Total			59.6600			59.6600	100%		1000000